

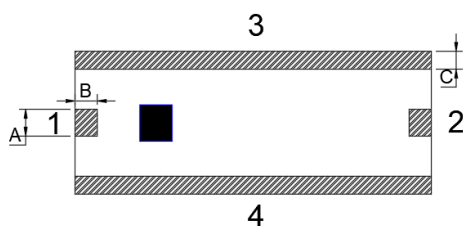
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

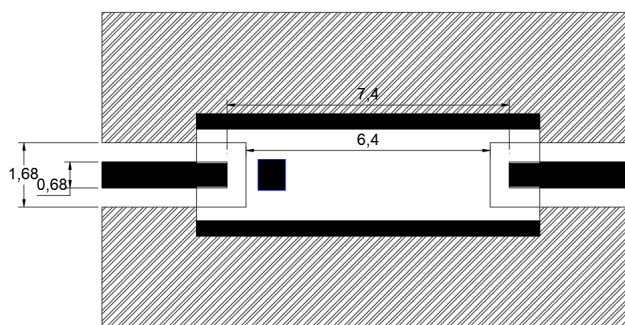
| NO.                                                              | Parameter                |        | SPEC    |
|------------------------------------------------------------------|--------------------------|--------|---------|
| 1                                                                | Frequency (MHz)          |        | 310~360 |
| 2                                                                | Insertion Loss (dB) @25℃ |        | ≤3.2    |
| 3                                                                | VSWR(In BW)              |        | ≤2.0    |
| 4                                                                | Attenuation(dB)          | 279MHz | ≥18     |
|                                                                  |                          | 396MHz | ≥28     |
| 5                                                                | In/Output Impedance (Ω)  |        | 50      |
| 6                                                                | Power                    |        | 5W      |
| Operating & Storage Condition (Component)                        |                          |        |         |
| Operation Temperature Range: -40℃ ~ +85℃                         |                          |        |         |
| Storage Temperature Range: -40℃~ +85℃                            |                          |        |         |
| Storage Condition before Soldering (Included packaging material) |                          |        |         |
| Storage Temperature Range: +5 ~ +40 ℃                            |                          |        |         |
| Humidity: 30 to 70% relative humidity                            |                          |        |         |

### Construction



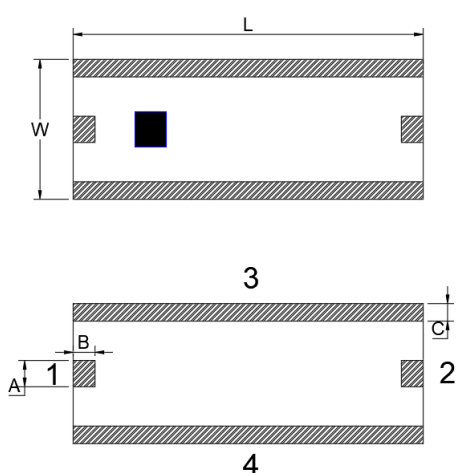
| PIN | Connection  |
|-----|-------------|
| 1   | Input Port  |
| 2   | Output Port |
| 3   | GND         |
| 4   | GND         |

### Mounting Considerations

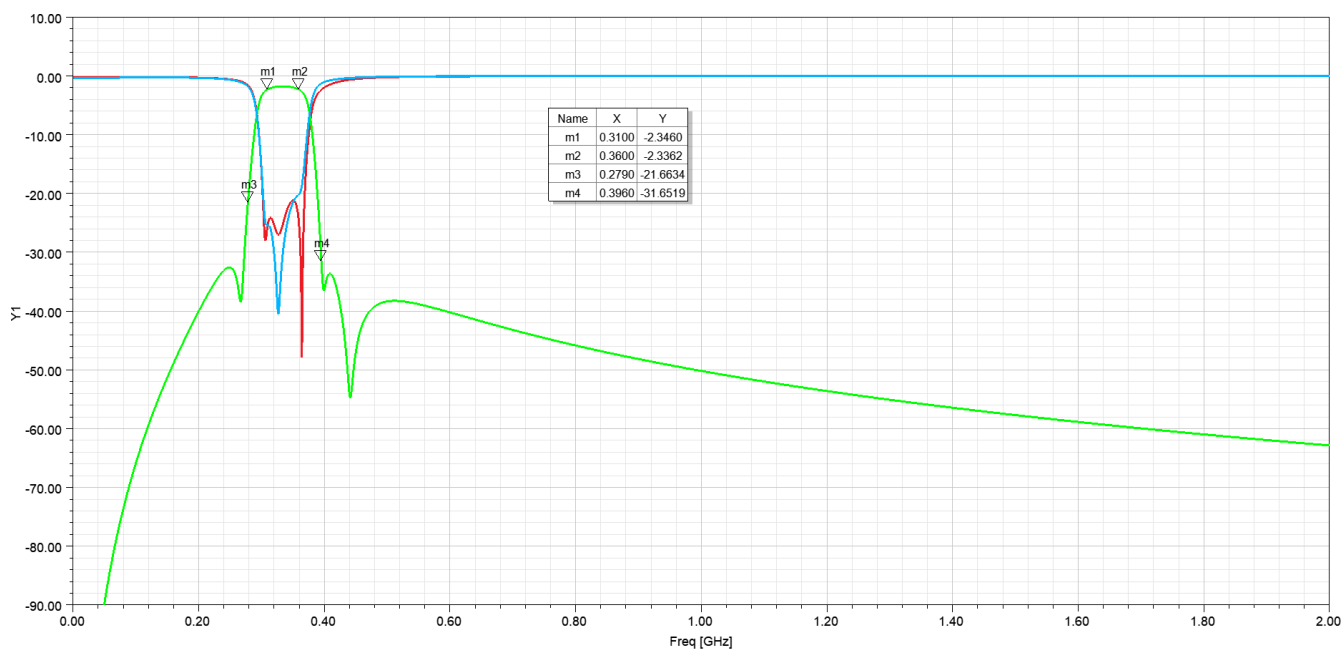


Unit: mm

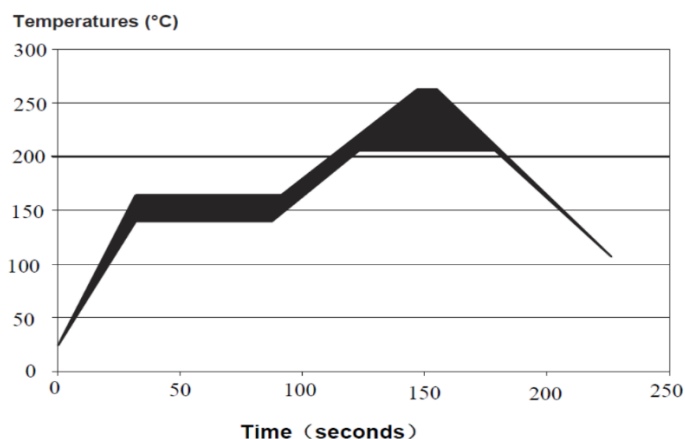
### Dimensions

| Figure                                                                            | Symbol | Dimension (mm) |
|-----------------------------------------------------------------------------------|--------|----------------|
|  | L      | 8.00 ± 0.20    |
|                                                                                   | W      | 3.20 ± 0.20    |
|                                                                                   | T      | 1.50 ± 0.20    |
|                                                                                   | A      | 0.60 ± 0.10    |
|                                                                                   | B      | 0.50 ± 0.10    |
|                                                                                   | C      | 0.40 ± 0.10    |

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.